

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.43214	100.0	8.32794
Subtotal				0.43214	100	8.32794
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.40105	100.0	27
Subtotal				1.40105	100	27
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02748	0.04	0.52948
	Copper alloy	Iron (Fe)	7439-89-6	0.06869	0.1	1.3237
	Copper alloy	Copper (Cu)	7440-50-8	68.59161	99.86	1,321.84682
	Subtotal				68.68778	100
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.5394	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.67017	16.0	90
	Filler	Silica fused	60676-86-0	21.89141	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.08757	0.3	1.6875
	Subtotal				29.18855	100
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.2387	100.0	4.6
	Subtotal				0.2387	100
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00259	5.0	0.04991
	Lead alloy	Silver (Ag)	7440-22-4	0.00129	2.5	0.02495
	Lead alloy	Lead (Pb)	7439-92-1	0.04791	92.5	0.92324
	Subtotal				0.05179	100
Total				100.00001	100	NaN

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